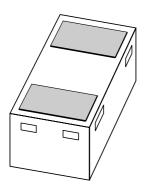
DISCRETE SEMICONDUCTORS

DATA SHEET



1PS10SB82Schottky barrier diode

Product specification

2003 Aug 20





Schottky barrier diode

1PS10SB82

FEATURES

- · Low forward voltage
- Low diode capacitance
- Leadless ultra small plastic package (1.0 mm × 0.6 mm × 0.5 mm)
- Boardspace 1.17 mm² (approx. 10% of SOT23)
- Power dissipation comparable to SOT23.

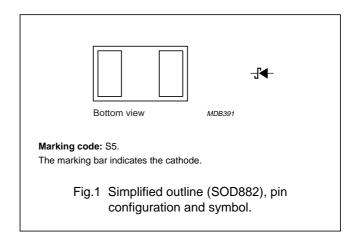
APPLICATIONS

- UHF mixers
- · Sampling circuits
- Modulators
- · Phase detectors
- Mobile communication, digital (still) cameras, PDA's and PCMCIA cards.

DESCRIPTION

An epitaxial Schottky barrier diode encapsulated in a SOD882 leadless ultra small plastic package.

ESD sensitive device, observe handling precautions.



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V_R	continuous reverse voltage	_	15	V
I _F	continuous forward current	_	30	mA
T _{stg}	storage temperature		+150	°C
T _i	junction temperature	_	150	°C

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ELECTRICAL CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _F	forward voltage	see Fig.2			
		I _F = 1 mA	_	340	mV
		I _F = 30 mA	_	700	mV
r _D	differential diode forward resistance	$f = 1 \text{ MHz}$; $I_F = 5 \text{ mA}$; see Fig.5	12	_	Ω
I _R	continuous reverse current	V _R = 1 V; see Fig.3; note 1	_	0.2	μΑ
C _d	diode capacitance	$V_R = 0 \text{ V}$; f = 1 MHz; see Fig.4	1	_	pF

Note

1. Pulse test: $t_p = 300 \,\mu s$; $\delta = 0.02$.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Refer to SOD882 standard mounting conditions (footprint), FR4 with 60 μm copper strip line.

Soldering

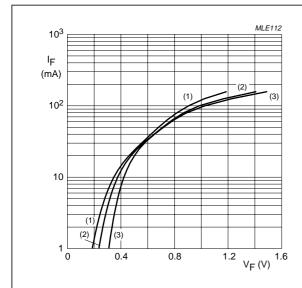
Reflow soldering is the only recommended soldering method.

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Schottky barrier diode

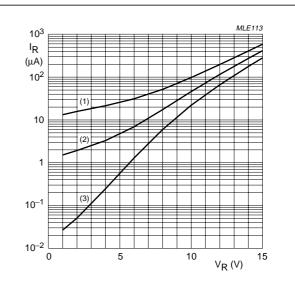
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GRAPHICAL DATA



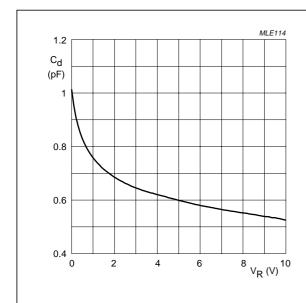
- (1) $T_{amb} = 125 \, ^{\circ}C$.
- (2) $T_{amb} = 85 \,^{\circ}C$.
- (3) $T_{amb} = 25 \, ^{\circ}C$.

Fig.2 Forward current as a function of forward voltage; typical values.



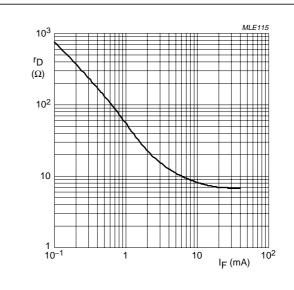
- (1) $T_{amb} = 125 \, ^{\circ}C$.
- (2) $T_{amb} = 85 \,^{\circ}C$.
- (3) $T_{amb} = 25 \, ^{\circ}C$.

Fig.3 Reverse current as a function of reverse voltage; typical values.



f = 1 MHz; $T_{amb} = 25$ °C.

Fig.4 Diode capacitance as a function of reverse voltage; typical values.



f = 1 MHz; $T_{amb} = 25$ °C.

Fig.5 Differential diode forward resistance as a function of forward current; typical values.

Philips Semiconductors Product specification

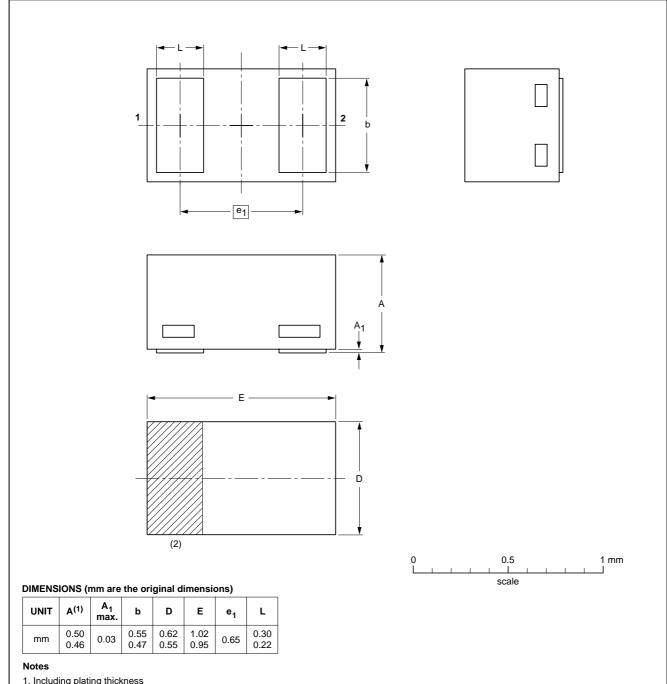
Schottky barrier diode

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PACKAGE OUTLINE

Leadless ultra small plastic package; 2 terminals; body 1.0 x 0.6 x 0.5 mm

SOD882



- 1. Including plating thickness
- 2. The marking bar indicates the cathode

OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOD882						03-04-16 03-04-17

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DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

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